

ABSTRACT OF THE DISCLOSURE

A flip-chip package is described. The flip-chip package includes a chip, a substrate, supporters and electrically conductive adhesive bumps. The electrically conductive adhesive bumps are located between the chip and the substrate electrically connecting the bonding pads on the former and the bump pads on the latter, wherein each electrically conductive adhesive bump has a smaller diameter at the central portion thereof than at the end portions thereof. The supporters are also disposed between the chip and the substrate surrounding the active area of the chip, so that the chip can be supported on the substrate.